

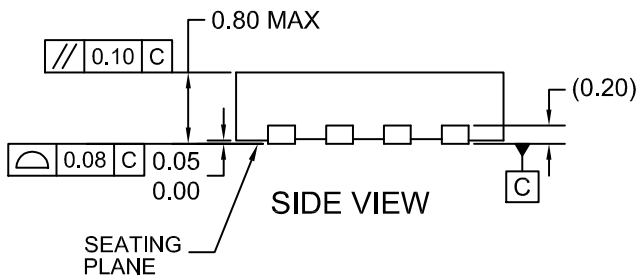
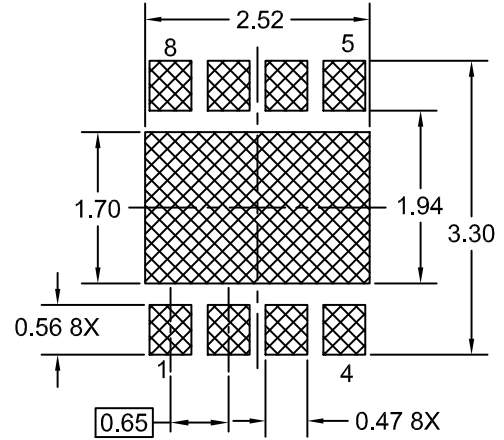
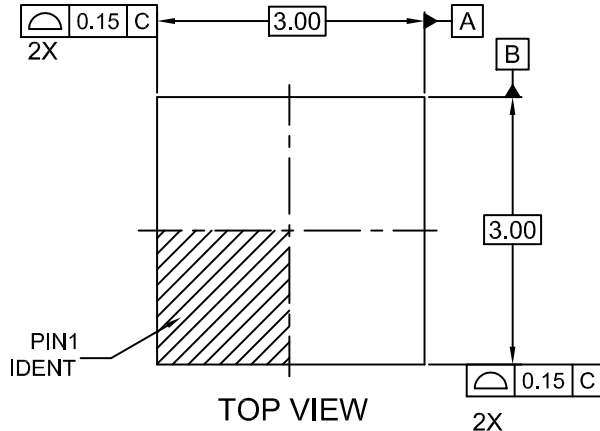
MECHANICAL CASE OUTLINE
PACKAGE DIMENSIONS

ON Semiconductor®

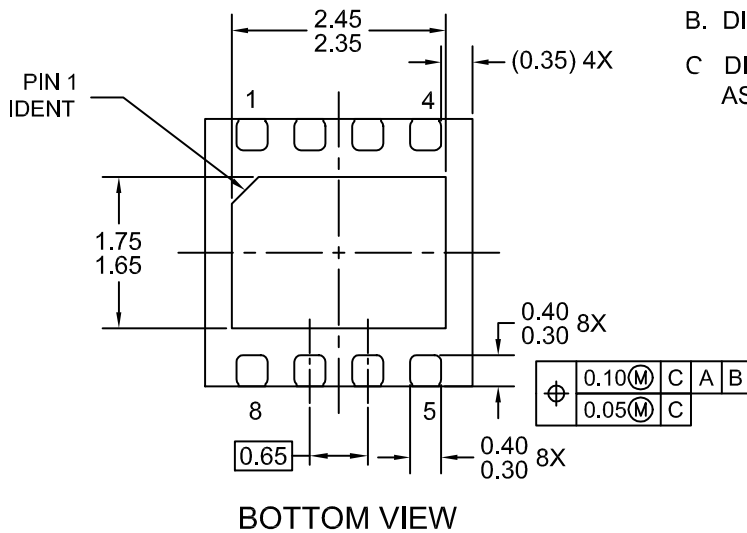


WDFN8 3x3, 0.65P
CASE 511DD
ISSUE O

DATE 31 JUL 2016



RECOMMENDED LAND PATTERN



NOTES:

- A: PACKAGE CONFORMS TO JEDEC MO-229 EXCEPT WHERE NOTED.
- B: DIMENSIONS ARE IN MILLIMETERS.
- C: DIMENSIONS AND TOLERANCES PER ASME Y14.5M, 1994.

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NEW STANDARD:		
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